CV110-3A elkular-b描在南自 Linearity Downconverter

- High dynamic range downconverter with integrated LO, IF, & RF amps
- RF: 800 960 MHz
- IF: 200 350 MHz
- +37 dBm Output IP3
- +20 dBm Output P1dB
- 5 dB Noise Figure
- +5V Single supply operation
- Pb-free 6mm 28-pin QFN package
- High-side LO configuration
- Common footprint with other PCS/UMTS versions

Specifications (1)

Product Description

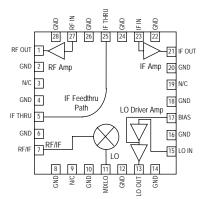
The CV110-3A is a high linearity downconverter designed to meet the demanding issues for performance, functionality, and cost goals of current and next generation mobile infrastructure. It provides high dynamic range performance in a low profile surfacemount leadless package that measures 6×6 mm square.

Functionality includes RF amplification, frequency conversion and IF amplification, while an integrated LO driver amplifier powers the passive mixer. The MCM is implemented with reliable and mature GaAs MESFET and InGaP HBT technology.

Typical applications include frequency downconversion used in CDMA/GSM/TDMA, CDMA2000, W-CDMA, and EDGE 2.5G and 3G mobile base transceiver stations for cellular frequency bands.

Functional Diagram

Product Information



Parameters	Units	Min	Тур	Max	Comments
RF Frequency Range	MHz		800 - 960		
LO Frequency Range	MHz		1000 - 1310		
IF Center Frequency Range	MHz		200 - 350		See note 2
% Bandwidth around IF center frequency	%		±7.5		See note 3
IF Test Frequency	MHz		240		
SSB Conversion Gain	dB		22		Temp = 25 °C
Gain Drift over Temp (-40 to 85 °C)	dB		±1.5		Referenced to +25 °C
Output IP3	dBm		+37		See note 4
Output IP2	dBm		+45		See note 4
Output 1dB Compression Point	dBm		+20		
Noise Figure	dB		5		See note 5
LO Input Drive Level	dBm	-2.5	0	+2.5	
LO-RF Isolation	dB		60		$P_{LO} = 0 dBm$
LO-IF Isolation	dB		40		$P_{LO} = 0 dBm$
Return Loss: RF Port	dB		15		
Return Loss: LO Port	dB		10		
Return Loss: IF Port	dB		15		
Operating Supply Voltage	V	+4.9	+5	+5.1	
Supply Current	mA	290	360	480	
FIT Rating	failures/1E9 hrs			72.1	@ 70° C ambient, 90% confidence
Junction Temperature	°C			160	See note 6

Specifications when using the application specific circuit (shown on page 3) with a low side LO = 0 dBm in a downconverting application over the operating case temperature range.
IF matching components affect the center IF frequency. Proper component values for other IF center frequencies than shown can be provided by emailing to applications.engineering@wj.com.
The IF bandwidth of the converter is defined as 15% around any center frequency in its operating IF frequency range. The bandwidth is determined with external components. Specifications are valid around

the total $\pm 7.5\%$ bandwidth. ie. with a center frequency of 240 MHz, the specifications are valid from 240 \pm 18 MHz. Assumes the supply voltage ± 5 V. OIP3 is measured with $\Delta f = 1$ MHz with IF_{out} ± 5 dBm / tone. Assumes LO injection noise is filtered at the thermal noise floor, ± 174 dBm/Hz, at the RF, IF, and Image frequencies.

6. The maximum junction temperature ensures a minimum MTTF rating of 1 million hours of usage

Absolute Maximum Rating

Parameter	Rating
Operating Case Temperature	-40 to +85 °C
Storage Temperature	-55 to +125 °C
DC Voltage	+6 V
Junction Temperature	+220 °C
RF Input (continuous)	+2 dBm

Ordering Information

Part No.	Description
CV110-3AF	Cellular-band High Linearity Downconverter (lead-free/RoHS-compliant 6x6mm QFN package)
CV110-3APCB240	Fully Assembled Eval. Board, $IF = 240MHz$

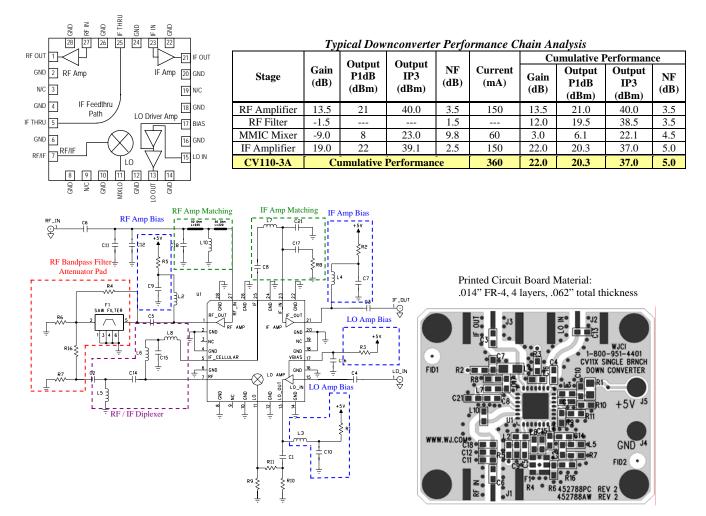
Operation of this device above any of these parameters may cause permanent damage.

Specifications and information are subject to change without notice

The Communications Edge TM

Product Information

Device Architecture / Application Circuit Information



CV110-3A: The application circuit can be broken up into four main functions as denoted in the colored dotted areas above: RF/IF diplexing (purple), amplifier matching (green), filtering (red), and dc biasing (blue). There are various placeholders for chip components in the circuit schematic so that a common PCB can be used for all WJ single-branch converters. Additional placeholders for other optional functions such as filtering are also included.

RF / **IF Amplifier Matching:** The RF amplifier requires a shunt matching element for optimal gain and input return loss performance. The IF amplifier requires matching elements to optimize the performance of the amplifier to the desired IF center frequency. Since IF bandwidths are typically on the order of 5 to 10%, a simple two element matching network, in the form of either a high-pass or low-pass filter structure, is sufficient to match the MMIC IF amplifier over these narrow bandwidths. Proper component values for other IF center frequencies can be provided by emailing to applications.engineering@wj.com.

RF Bandpass Filtering: Bandpass filtering is recommended to reject the image frequencies and achieve the best noise figure

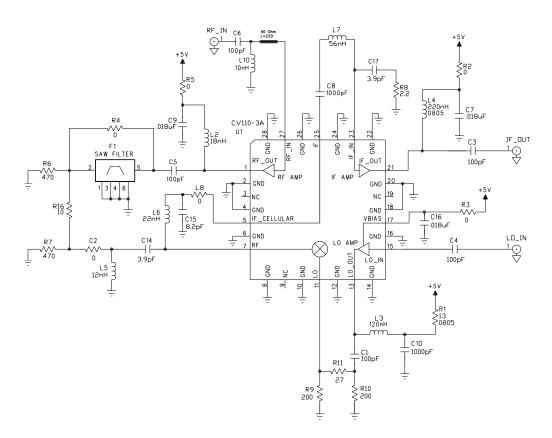
performance with the downconverter. The bandpass filter, implemented with a SAW filter on the application circuit, allows for the suppression of noise from the image frequency. It is permissible to not use a filter and use a 2 dB pad with R6, R7, and R16 instead with slightly degraded noise figure performance. Standard WJ evaluation boards will have the 2 dB pad in place.

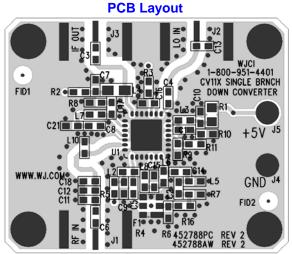
External Diplexer: In a downconversion application, the incoming RF signal impinges on the switching elements of the mixer; the interaction with these switches produces a signal at the IF frequency. The two signals (RF and IF) are directed to the appropriate ports by the external diplexer. Pin 5 contains the IF signal and allows the signal to be transferred to pin 25 for the convenience of PCB layouts.

DC biasing: DC bias must be provided for the RF, LO and IF amplifiers in the converter. R1 sets the operating current for the last stage of the LO amplifier and is chosen to optimize the mixer LO drive level. Proper RF chokes and bypass capacitors are chosen for proper amplifier biasing at the intended frequency of operation. The "+5 V" dc bias should be supplied directly from a voltage regulator.

Product Information

Downconverting Application Circuit: CV110-3APCB240 RF = 800 – 960 MHz, IF = 240 MHz

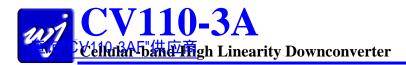




Circuit Board Material: .014" FR-4, 4 layers, .062" total thickness

Bill of Materials			
Ref. Desig.	Component		
R1	13 Ω chip resistor, size 0805		
R2, R3, R4, R5, C2, L8	0Ω chip resistor		
R6, R7	470 Ω chip resistor		
R8	2.2Ω chip resistor		
R9, R10	200 Ω chip resistor		
R11	27 Ω chip resistor		
R16	10 Ω chip resistor		
C1, C3, C4, C5, C6	100 pF chip capacitor		
C7, C9, C16	0.018 µF chip capacitor		
C8, C10	1000 pF chip capacitor		
C11, C12, C13,	Shown in silkscreen, but not		
C18, C21, F1	used in actual circuit.		
C15	8.2 pF chip capacitor		
C14, C17	3.9 pF chip capacitor		
C18	1.5 pF chip capacitor		
L2	18 nH chip inductor		
L3	120 nH chip inductor		
L4	220 nH chip inductor, size 0805		
L5	12 nH chip inductor		
L6	22 nH chip inductor		
L7	56 nH chip inductor		
L10	10 nH chip inductor		
U1	CV110-3A WJ Converter		

All components are of size 0603 unless otherwise specified.

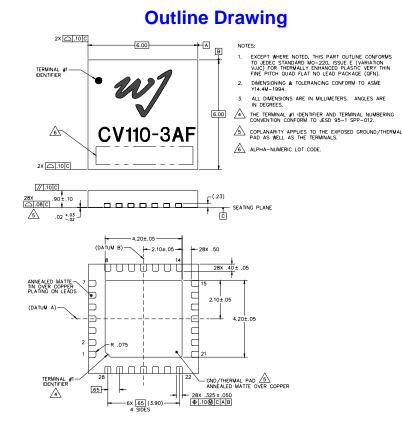


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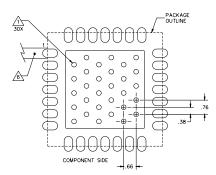
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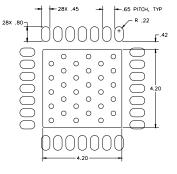
CV110-3AF Mechanical Information

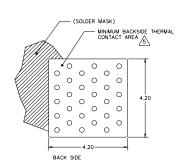
This package is lead-free/RoHS-compliant. It is compatible with both lead-free (maximum 260°C reflow temperature) and leaded (maximum 245°C reflow temperature) soldering processes. The plating material on the pins is annealed matter tin over copper.



Mounting Configuration / Land Pattern







NOTES:

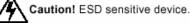
- GROUND/THERMAL VIAS ARE CRITICAL FOR THE PROPER PERFORMANCE OF THIS DEVICE. VIAS SHOULD USE A .35mm (#80/.0135") DIAMETER DRILL AND HAVE A FINAL, PLATED THRU DIAMETER OF .25mm (.010").
- ADD AS MUCH COPPER AS POSSIBLE TO INNER AND OUTER LAYERS NEAR THE PART TO ENSURE OPTIMAL THERMAL PERFORMANCE.
- TO ENSURE RELIABLE OPERATION, DEVICE GROUND PADDLE-TO-GROUND PAD SOLDER JOINT IS CRITICAL.
- 4. ADD MOUNTING SCREWS NEAR THE PART TO FASTEN THE BOARD TO A HEATSINK. ENSURE THAT THE GROUND/THERMAL VIA REGION CONTACTS THE HEATSINK
- DO NOT PUT SOLDER MASK ON THE BACK SIDE OF THE PC BOARD IN THE REGION WHERE THE BOARD CONTACTS THE HEATSINK.
- AD CONSTRUCTION.
- AND CONSTRUCTION. 7. USE 1 OZ. COPPER MINIMUM.
- 8. ALL DIMENSIONS ARE IN MILLIMETERS. ANGLES ARE IN DEGREES.

Product Marking

The component will be lasermarked with a "CV110-3AF" product label with an alphanumeric lot code on the top surface of the package.

Tape and reel specifications for this part will be located on the website in the "Application Notes" section.

ESD / MSL Information



ESD Rating: Value:	Class 1B Passes ≥ 500 V to <1000 V
Test:	Human Body Model (HBM)
Standard:	JEDEC Standard JESD22-A114

ESD Rating: Class III

Value:	Passes $\geq 500V$ to $<1000V$
Test:	Charged Device Model (CDM)
Standard:	JEDEC Standard JESD22-C101

MSL Rating: Level 2 at +260°C convection reflow Standard: JEDEC Standard J-STD-020

Functional Pin Layout

Pin	FUNCTION	Pin	FUNCTION
1	RF Amp Output	15	LO Amp Input
2	GND	16	GND
3	N/C	17	LO Amp Bias
4	GND	18	GND
5	IF Feedthru Port	19	N/C or GND
6	GND	20	GND
7	Mixer RF /	21	IF Amp
/	IF Port		Output/Bias
8	GND	22	GND
9	N/C or GND	23	IF Amp Input
10	GND	24	GND
11	Mixer LO Input	25	IF Feedthru Port
12	GND	26	GND
13	LO Amp Output	27	RF Amp Input
14	GND	28	GND

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